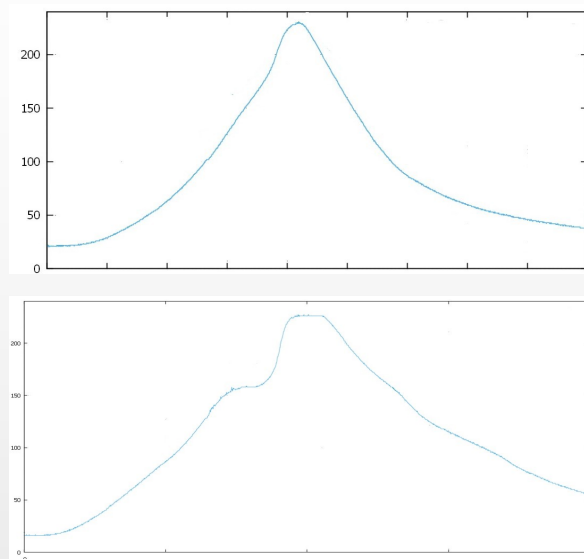


MINI-CONDENS-IT PROFILER

Condensation Reflow Soldering Machine

Vapor Phase Reflow Soldering Machine for Hobby and Laboratory single pieces up to small quantities



Description

The **IMDES MINI CONDENS-IT PROFILER** is designed for reflow soldering laboratory and prototype, single pieces and small quantities PCB's. Components such as QFPs, BGAs, Flip-Chips as well as hybrids are processed defect free with highest quality results. Due the small footprint of the **MINI CONDENS-IT PROFILER** it may be used at any place.

Features

- Table model Top loader
- **Adjustable temperature profiles in the pre-heating zone (CVPRS*)**
- **Adjustable TAL Time Above Liquid**
- **ATS Anti Tomb Stone modus**
- **Micro USB for the transfer of solder profile data to PC**
- Window to observe the soldering process
- Suitable for BGA's, Stacked Packages
- Oxygen Free Soldering
- Homogeneous temperature transmission on the complete Assembly
- No over heating of components

MINI CONDENS IT PROFILER		Order No.	Price Each
IMDES Vapor Phase soldering machine MINI CONDENS IT PROFILER , excluding transfer medium		IMD-MNI-PROF1	
Medium basic filling Galden LS230 Reflow Fluid for lead free applications Quantity 0,5 Liter = 910 Gram		IMD-GL 230-05GF	
Energy supply (Single Phase + ground)	220-240 Volt / 50-60 Hz		
Power drawn	1.000 Watt (ca. 5 A)		
System dimensions.	400 x 315x 305 mm (L x B x H)		
max. solder product format	240 x 170 x 20 mm (L x B x H) <i>(PCB's up to double Euro card format)</i>		
Standard cycle time	10 Min		
Soldering time	ca. 60 – 90 Seconds		
Process temperature (depends on medium type)	150 up to 240 °C		
Weight	ca. 6 kg		
Cooling	Forced air cooling		
Heat transfer medium	GALDEN with the correct boiling temperature (max. 240 °C) higher Temperature is not possible		
Medium basic filling quantity	ca. 450– 500 ml GALDEN		